



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-02-22
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacobello	Representative Title	IPD MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L6932D2.5	A507*UD34CA6	A	MUAR B/E	2016-02-22
Amount	UoM	Unit type	ST ECOPACK Grade	
76.29	mg	Each	ECOPACK1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	NiPdAu	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.9, 6, 1.75	8	GULL WING	
Comment	SO 08 .15 JEDEC			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	AS07*UD34CA6						
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Die	Other inorganic materials	4.664	mg	supplier	die	Silicon (Si)	7440-21-3		4.453	mg	954760	58369	
				supplier	metallization	Aluminium (Al)	7429-90-5		0.029	mg	6218	380	
				supplier	metallization	Tungsten (W)	7440-33-7		0.046	mg	9863	603	
				supplier	Passivation	Silicon Nitride	12033-89-5		0.007	mg	1501	92	
				supplier	Passivation	Silicon Oxide	7631-86-9		0.069	mg	14794	904	
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.003	mg	643	39	
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.023	mg	4931	301	
				supplier	polymer die coating	PIXI Gamma-butyrolactone	96-48-0		0.034	mg	7290	446	
Leadframe	Copper & its alloys	32.031	mg	supplier	alloy	Copper (Cu)	7440-50-8		31.911	mg	996254	418285	
				supplier	alloy	Iron (Fe)	7439-89-6		0.015	mg	468	197	
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.027	mg	843	354	
				supplier	metallization	Nickel (Ni)	7440-02-0		0.071	mg	2217	931	
				supplier	metallization	Palladium (Pd)	7440-05-3		0.005	mg	156	66	
				supplier	metallization	Gold (Au)	7440-57-5		0.002	mg	62	26	
Die attach	Other Organic Materials	1.050	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.788	mg	750476	10329	
				supplier	glue or tape	Epoxy Cresol Novolak	29690-82-2		0.258	mg	245714	3382	
				supplier	glue or tape	1-isopropyl-2,2-dimethyltrimethylene diisobutyl	6846-50-0		0.004	mg	3810	52	
Bonding wires	Other inorganic materials	0.234	mg	supplier	wire	Gold (Au)	7440-57-5		0.234	mg	1000000	3067	
Encapsulation	Other Organic Materials	38.311	mg	supplier	mold compound	Silica, vitreous	60676-86-0		30.649	mg	800005	401743	
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		3.831	mg	99997	50216	
				supplier	mold compound	phenol resin	9003-35-4		1.916	mg	50012	25115	
				supplier	mold compound	Brominated epoxy resin	40039-93-8		0.766	mg	19994	10041	
				supplier	mold compound	Antimony Trioxide	1309-64-4		0.766	mg	19994	10041	
				supplier	mold compound	Carbon Black	1333-86-4		0.383	mg	9997	5020	